

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

B1
Claim 1. (Currently Amended): An adhesive composition comprising i) a polychloroprene dispersion, and ii) at least one adhesive resin, wherein the polychloroprene dispersion i) is a reaction product of an emulsion polymerization that comprises a) chloroprene, b) at least one ethylenically unsaturated monomer that is copolymerizable with chloroprene and c) as emulsifier, mixtures of abietic acid and other tricyclic diterpenecarboxylic acid ^(S) having at least two conjugated C=C double bonds per molecule.

Claim 2. (Original): The adhesive composition of Claim 1 comprising 100 parts by weight of a polychloroprene dispersion containing as emulsifier a tricyclic diterpenecarboxylic acid having at least two conjugated C=C double bonds per molecule, 15 to 75 parts by weight of an adhesive resin and 1 to 10 parts of a metal oxide comprising a member selected from the group consisting of zinc oxide and magnesium oxide.

Claim 3. (Original): The adhesive composition of Claim 1 wherein the adhesive composition has an open time after evaporation of the water of 4 to 15 days.

Claim 4. (Previously Amended): The adhesive composition of Claim 2 wherein the adhesive resin comprises a terphenol resin having a softening point above 110°C.

Claim 5. (Previously Amended): A process for preparing an adhesive composition comprising combining i) a polychloroprene dispersion, and ii) an adhesive resin, wherein the polychloroprene dispersion i) is prepared by emulsion polymerization that comprises reacting a) chloroprene with b) from 2 to 20 parts by weight of 2,3-dichlorobutadiene in the presence of c) from 1 to 10 parts by weight of mixtures of abietic acid and other ^(S) tricyclic diterpenecarboxylic acid having at least two

conjugated C=C double bonds per molecule as emulsifier, wherein amounts in the emulsion polymerization reaction are based on 100 parts by weight of a) and b).

β1
Claim 6. (Original): A contact adhesive for bonding inorganic or organic substrates comprising the adhesive composition of Claim 1.

Claim 7. (New): An adhesive composition comprising:

- β2
- i) a polychloroprene dispersion comprising the reaction product of an emulsion polymerization that comprises a) chloroprene, b) at least one ethylenically unsaturated monomer that is copolymerizable with chloroprene and c) as emulsifier, an unmodified resin acid comprising at least 40% by weight of abietic acid; and
 - ii) at least one adhesive resin comprising a terpenephenol resin having a softening point above 110°C.

Claim 8. (New): The adhesive composition of Claim 7 comprising 100 parts by weight of the polychloroprene dispersion in i), 15 to 75 parts by weight of the adhesive resin ii), and 1 to 10 parts of a metal oxide comprising a member selected from the group consisting of zinc oxide and magnesium oxide.

Claim 9. (New): The adhesive composition of Claim 1 wherein the adhesive composition has an open time after evaporation of the water of 4 to 15 days.

Claim 10. (New): A process for preparing an adhesive composition comprising combining i) a polychloroprene dispersion, and ii) an adhesive resin, wherein the polychloroprene dispersion i) is prepared by emulsion polymerization that comprises reacting a) chloroprene with b) from 2 to 20 parts by weight of 2,3-dichlorobutadiene in the presence of c) from 1 to 10 parts by weight of an unmodified resin acid comprising at least 40% by weight of abietic acid as emulsifier; wherein amounts in the emulsion polymerization reaction are based on 100 parts by weight of a) and b) and the adhesive resin comprises at least one terpenephenol resin having a softening point above 110°C.

Claim 11. (New): A contact adhesive for bonding inorganic or organic substrates comprising the adhesive composition of Claim 7.

B2
Claim 12. (New): An adhesive composition comprising i) a polychloroprene dispersion, ii) at least one adhesive resin, and iii) a thickening agent; wherein the polychloroprene dispersion i) is a reaction product of an emulsion polymerization that comprises a) chloroprene, b) at least one ethylenically unsaturated monomer that is copolymerizable with chloroprene and c) as emulsifier, an unmodified resin acid comprising at least 40% by weight of abietic acid.

Claim 13. (New): The adhesive composition of Claim 12 comprising 100 parts by weight of the polychloroprene dispersion in i), 15 to 75 parts by weight of the adhesive resin ii), and 1 to 10 parts of a metal oxide comprising a member selected from the group consisting of zinc oxide and magnesium oxide.

Claim 14. (New): The adhesive composition of Claim 13, wherein the thickening agent comprises one or more organic thickening agents present in the adhesive composition at from 0.01 to 1 wt.%, based on the adhesive composition.

Claim 15. (New): The adhesive composition of Claim 13, wherein the organic thickening agent is one or more materials selected from the groups consisting of cellulose derivatives, alginates, starch, starch derivatives or polyacrylic acid.

Claim 16. (New): The adhesive composition of Claim 13, wherein the thickening agent comprises one or more inorganic thickening agents present in the adhesive composition at from 0.05 to 5 wt.% based on the adhesive composition.

Claim 17. (New): The adhesive composition of Claim 16, wherein the inorganic thickening agent comprises bentonite.

Claim 18. (New): The adhesive composition of Claim 12 wherein the adhesive composition has an open time after evaporation of the water of 4 to 15 days.

B2
Claim 19. (New): The adhesive composition of Claim 12 wherein the adhesive resin comprises a terphenol resin having a softening point above 110°C.

Claim 20. (New): A contact adhesive for bonding inorganic or organic substrates comprising the adhesive composition of Claim 12.
